**3GPP TSG-RAN WG2 #126 R2-2406148**

**Maastricht, Netherlands, August 19th - 23rd , 2024**

**Title:** **Draft** Reply LS on Rel-18 higher-layers parameter list

**Response to:** R2-2400020/R1-2312710 LS on Rel-18 higher-layers parameter list

**Release:** Release 18

**Work Item:** NR\_MC\_enh-Core, NR\_MIMO\_evo\_DL\_UL-Core, NR\_pos\_enh2-Core, Netw\_Energy\_NR, NR\_cov\_enh2, NR\_XR\_enh-Core, NR\_Mob\_enh2, NR\_BWP\_wor-Core, NR\_NTN\_enh, IoT\_NTN\_enh-Core, NR\_SL\_enh2-Core, NR\_NetConRepeater, NR\_DSS\_enh, NR\_redcap\_enh-Core TEI18

**Source: Ericsson [**RAN2]

**To:** RAN1

**Cc:** RAN3, RAN4

**Contact person:** Håkan Palm

 hakan (dot) l (dot) palm (at) ericsson (dot) com

**Send any reply LS to: 3GPP Liaisons Coordinator,** **mailto:3GPPLiaison@etsi.org**

**Attachments:** R2-2407570 ASN.1 names in RAN1 parameter list Rev 1

# 1 Overall description

In LS R2- 2406148/R1-2405787, RAN2 provided a first version of the parameter list with the names used in ASN.1. It was later discovered that the RAN2 names in the tables should be revised to reflect the ASN.1 names.

Attached is the RAN1 parameter list with revised ASN.1 parameter names. The following tables are modified:

|  |  |
| --- | --- |
| MIMO | Some changes and comments, shaded blue |
| Pos | Corrected names shaded blueNames added for 38.355 and 37.355 |
| Mobility | RAN2 columns filled in |
| NR-NTN | ASN1 names added for 37.355 |
| TEI18-1symbolPRS | “-r17” added for some fields |
| TEI18-Multiple PUSCHs scheduling by single DCI for non-consecutive slots in FR1 | “-r17” added for some fields |
| TEI18-Multiple PUSCHs scheduling by single DCI for non-consecutive slots in FR1 | “-r17” added for some fields |
| TEI18\_PL RS Type 1 CG | “-r18” added for some fields |
|  |  |

# 2 Actions

**To RAN1:**

**ACTION:** RAN2 respectfully asks RAN1 to take the parameter names in the attached list into consideration in their work.

# 3 Dates of next TSG RAN WG2 meetings

TSG RAN WG2 Meeting #127-bis 14-18 Oct 2024, Hefei, China

TSG RAN WG2 Meeting #128 18-22 Nov 2024, Orlando, US